



## Advanced Welding and Soldering Technologies for Metals and Alloys

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submissions:

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### Message from the Guest Editor

Dear Colleagues ,

The subject of this Special Issue oscillates around welding and soldering. In the case of the welding process, the subject of the work will be oriented to all welding methods (MMA, MIG/MAG, GTAW, SAW, PAW, LBW, EBW, and others) and thermal processes occurring during welding, as well as welding metallurgy in terms of the analysis of processes occurring in the liquid weld pool metal. The thematic area of this work also includes innovative research on joining difficult-to-weld materials and compiled welded structures, in particular thin-walled welded structures. The use of numerical and computer simulation of the welding process, for example in the aspect of analyzing temperature or stress distribution in the area of the welded joint, are topics covered by this work. The work will present new solutions in the field of soldering methods concerning fillers and fluxes used to produce unconventional soldered joints from various materials. We encourage you to publish research on the broadly understood minimization of defects in welded and soldered joints using innovative technological, material, and construction solutions.





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## Editor-in-Chief

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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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